Zener Diode

DZ2J330×0L

# **Panasonic**

# DZ2J330×0L

# Silicon epitaxial planar type

For constant voltage / For surge absorption circuit

### ■ Features

- · Excellent rising characteristics of zener current Iz
- · Low zener operating resistance Rz
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: HG or HR

# ■ Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

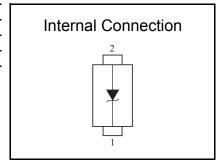
■ Absolute Maximum Ratings Ta = 25 °C

Parameter	Symbol	Rating	Unit
Repetitive peak forward current	IFRM	200	mA
Total power dissipation *1	PT	200	mW
Electrostatic discharge *2	ESD	±8	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tstg	-55 to +150	°C

Note) \*1 Mounted on glass epoxy print board (  $45 \text{ mm} \times 45 \text{ mm} \times 1 \text{ mm}$  ) Solder in ( Recommended land pattern )

\*2 Test method : IEC61000\_4\_2 ( C = 150 pF, R = 330  $\Omega$ , Contact discharge : 10 times )

# 1. 25 0. 13 0. 35 0. 35 0. 5 0. 7 1. Cathode 2. Anode Panasonic SMini2-F5-B JEITA SC-90A Code —



## ■ Electrical Characteristics Ta = 25 °C ± 3 °C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	VF	IF = 10 mA			1.0	V
Zener voltage *1, *2	VZ	IZ = 2 mA	31.35		34.65	V
Zener operating resistance	RZ	IZ = 2 mA			200	Ω
Zener rise operating resistance	RZK	IZ = 0.5 mA			200	Ω
Reverse current	IR	VR = 25 V			0.05	μΑ
Temperature coefficient of zener voltage *3	SZ	IZ = 2 mA		32.0		mV/°C

- Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.
  - 2. Absolute frequency of input and output is 5 MHz.
  - 3. \*1 The temperature must be controlled 25 °C for VZ mesurement. VZ value measured at other temperature must be adjusted to VZ (25 °C).
    - \*2 VZ guaranted 20 ms after current flow

\*3 Tj = 25 °C to 150 °C

Rank classification

Code	M			0		
Rank	M		No-rank			
VZ	32.20	to	33.80	31.35	to 34.65	
Marking symbol	HR		HG			

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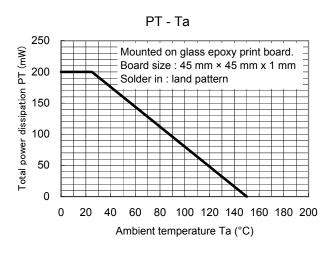
Established: 2009-10-14 Revised: 2013-07-16

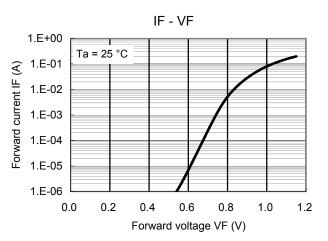
# **Panasonic**

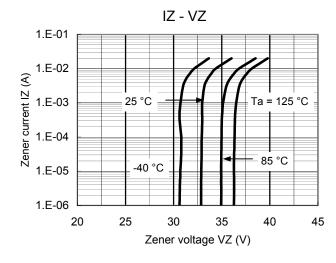
Zener Diode

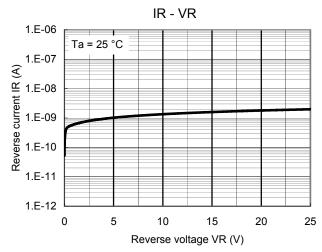
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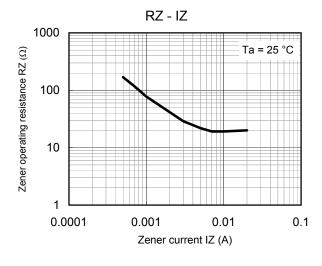
# Technical Data (reference)

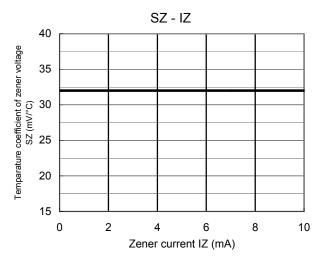












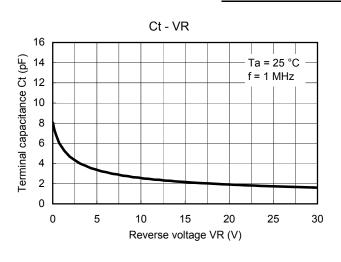
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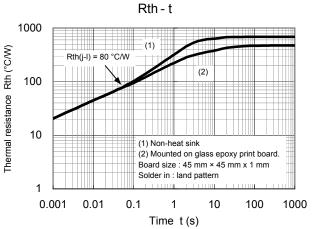
Revision. 3

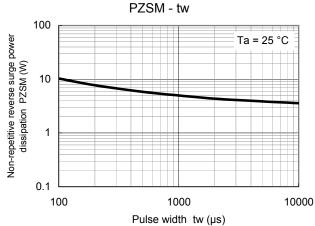
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# Technical Data (reference)







Established: 2009-10-14

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: 2013-07-16

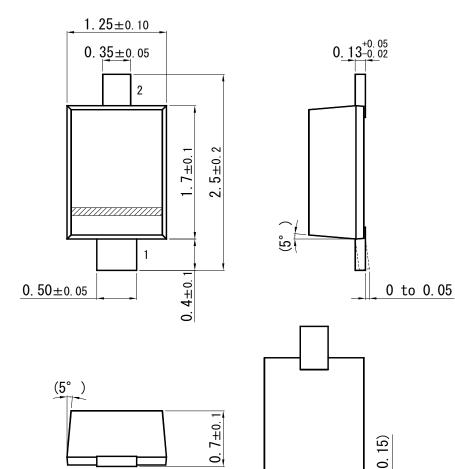
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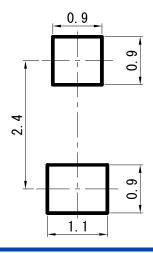
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# SMini2-F5-B

Unit: mm



# ■ Land Pattern (Reference) (Unit: mm)



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Established: 2009-10-14 Revised: 2013-07-16

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